

Features

- ★ 100V, 75A
 $R_{DS(ON)} < 9.2m\Omega @ V_{GS} = 10V$
 $R_{DS(ON)} < 13.5m\Omega @ V_{GS} = 4.5V$
- ★ Advanced Split Gate Trench Technology
- ★ Excellent $R_{DS(ON)}$ and Low Gate Charge
- ★ Lead free product is acquired

Product Summary

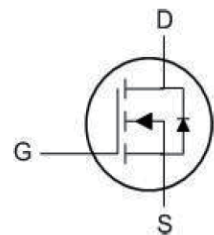
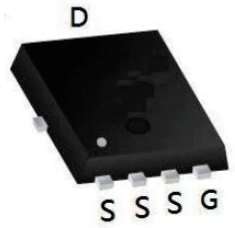
RoHS

| BVDSS | RDSON | ID |
|-------|-------|-----|
| 100V | 7.3mΩ | 75A |

Description

- ★ Load Switch
- ★ PWM Application
- ★ Power management

PRPAK5X6 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Max. | Units |
|-----------------|---|---------------------|-------|
| V_{DSS} | Drain-Source Voltage | 100 | V |
| V_{GSS} | Gate-Source Voltage | ±20 | V |
| I_D | Continuous Drain Current | $T_C = 25^\circ C$ | 75 |
| | | $T_C = 100^\circ C$ | 49 |
| I_{DM} | Pulsed Drain Current <small>note1</small> | 300 | A |
| EAS | Single Pulsed Avalanche Energy <small>note2</small> | 90 | mJ |
| P_D | Power Dissipation | 97 | W |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 1.3 | °C/W |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to 150 | °C |

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|---|---|------|------|-----------|-----------|
| Off Characteristic | | | | | | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 100 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=100V, V_{GS}=0V,$ | - | - | 1 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{DS}=0V, V_{GS}=\pm 20V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1 | 1.6 | 2.5 | V |
| $R_{DS(on)}$ | Static Drain-Source on-Resistance <small>note3</small> | $V_{GS}=10V, I_D=20A$ | - | 7.3 | 9.2 | $m\Omega$ |
| | | $V_{GS}=4.5V, I_D=8A$ | - | 9 | 13.5 | $m\Omega$ |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS}=50V, V_{GS}=0V,$ $f=1.0MHz$ | - | 2046 | - | pF |
| C_{oss} | Output Capacitance | | - | 865 | - | pF |
| C_{riss} | Reverse Transfer Capacitance | | - | 25 | - | pF |
| Q_g | Total Gate Charge | $V_{DS}=50V, I_D=30A,$ $V_{GS}=10V$ | - | 39.4 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 5.2 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 9.8 | - | nC |
| Switching Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD}=50V, I_D=25A,$ $R_G=6\Omega, V_{GS}=10V$ | - | 20 | - | ns |
| t_r | Turn-on Rise Time | | - | 5.2 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 49 | - | ns |
| t_f | Turn-off Fall Time | | - | 12 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I_S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 75 | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 300 | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{GS}=0V, I_S=30A$ | - | - | 1 | V |
| t_{rr} | Body Diode Reverse Recovery Time | $T_J=25^\circ C,$ $I_F=12A, dI/dt=100A/\mu s$ | - | 49 | - | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | | - | 85 | - | nC |

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition: $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega, L=0.5mH, I_{AS}=19A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Electrical and Thermal Characteristics (Curves)

Figure 1: Output Characteristics

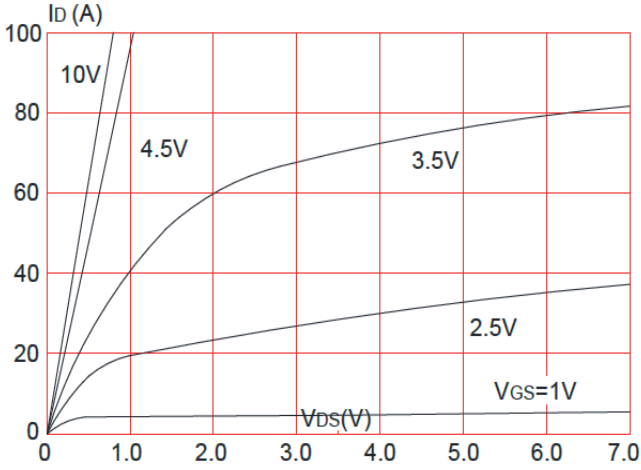


Figure 2: Typical Transfer Characteristics

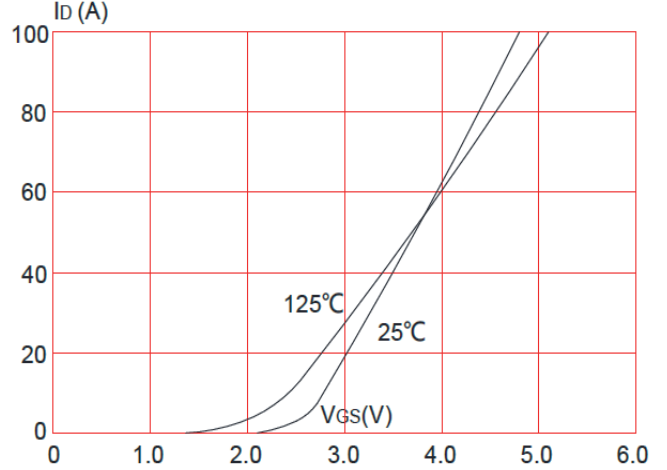


Figure 3: On-resistance vs. Drain Current

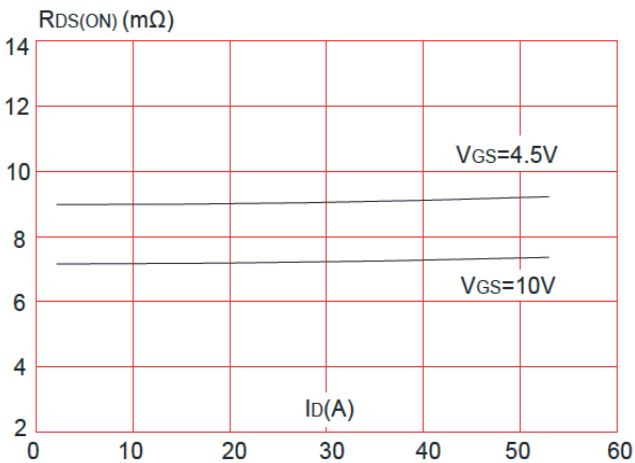


Figure 4: Body Diode Characteristics

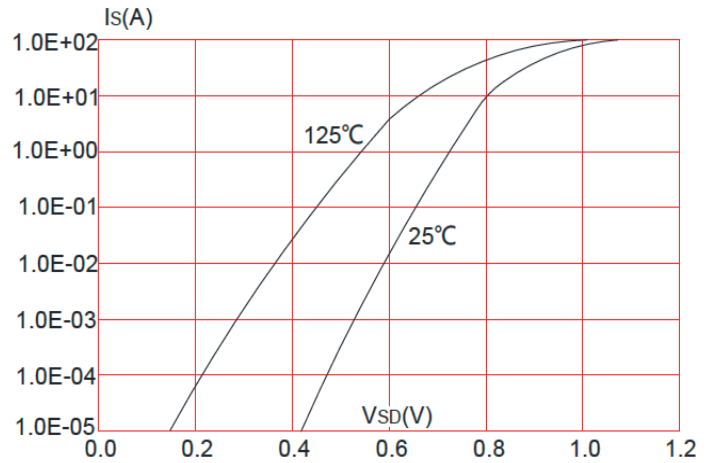


Figure 5: Gate Charge Characteristics

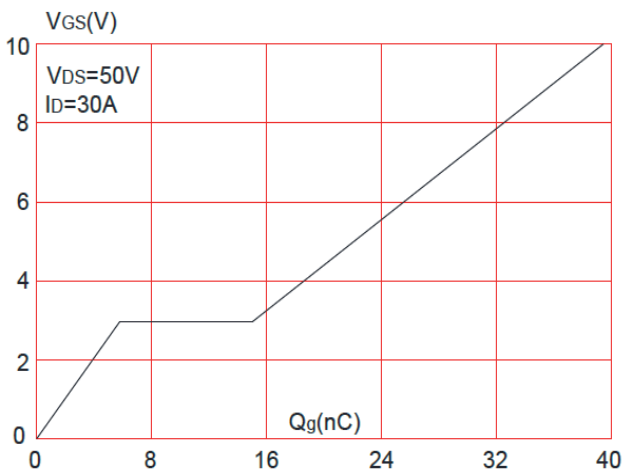
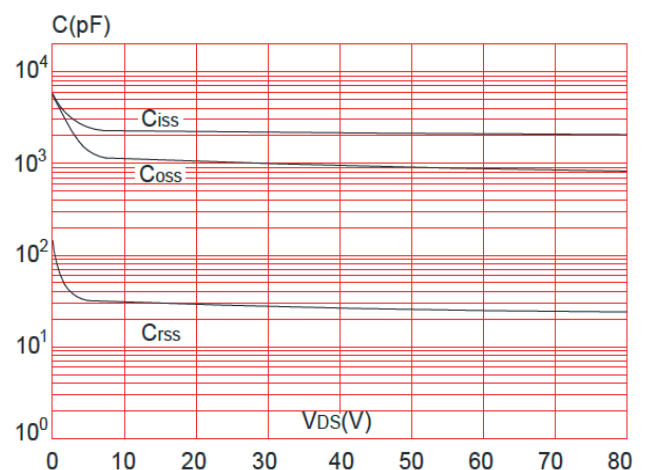


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

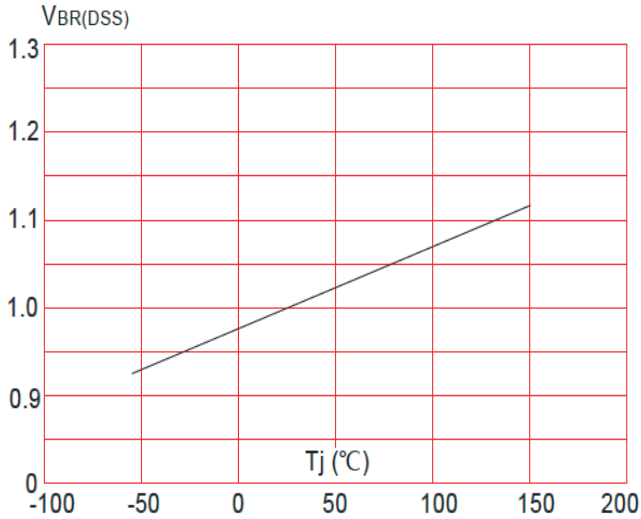


Figure 8: Normalized on Resistance vs. Junction Temperature

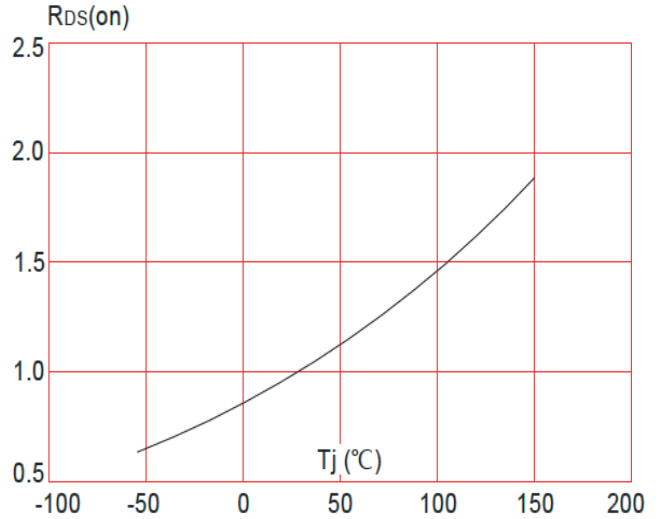


Figure 9: Maximum Safe Operating Area

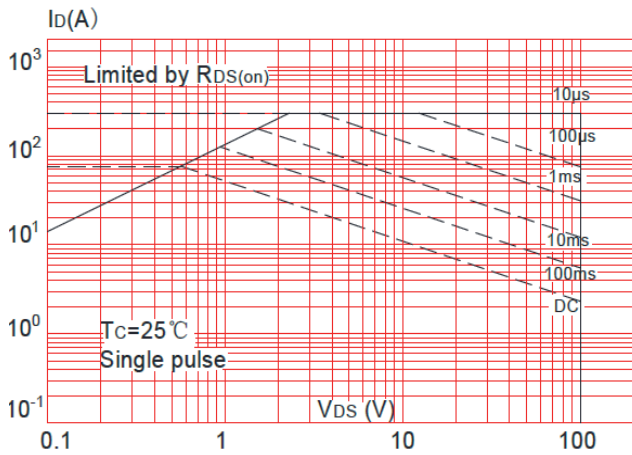


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

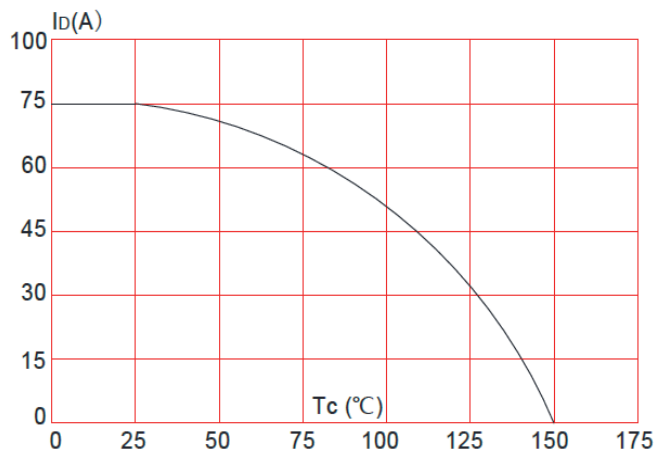
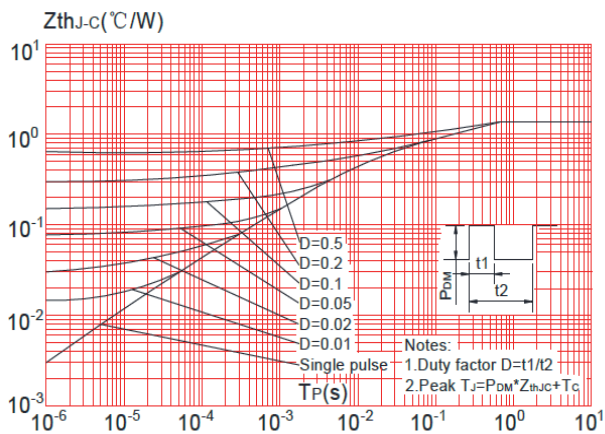


Figure 11 Maximum Effective Transient Thermal Impedance vs. Junction Temperature



Test Circuit

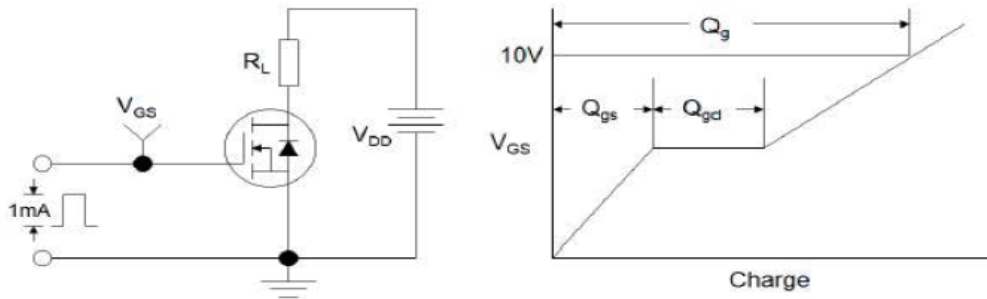


Figure 1: Gate Charge Test Circuit & Waveform

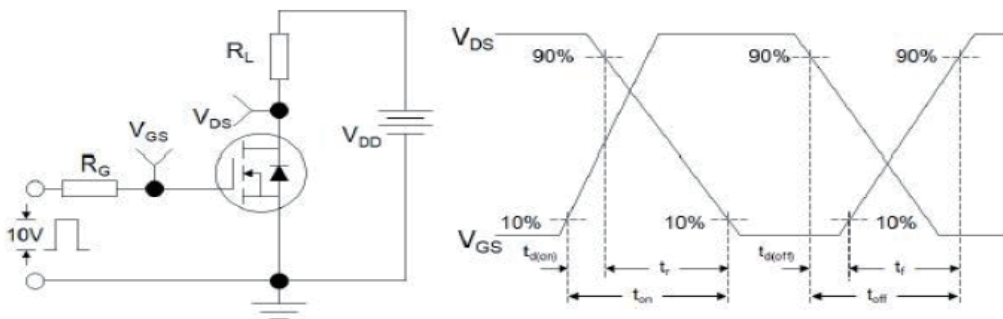


Figure 2: Resistive Switching Test Circuit & Waveforms

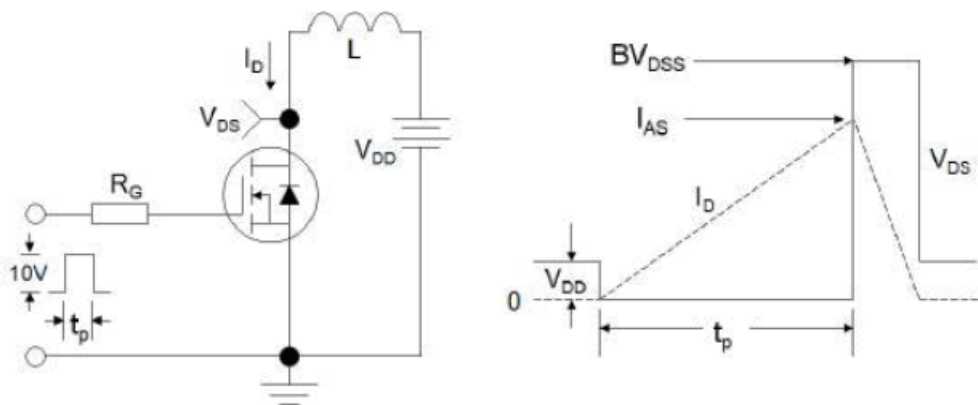
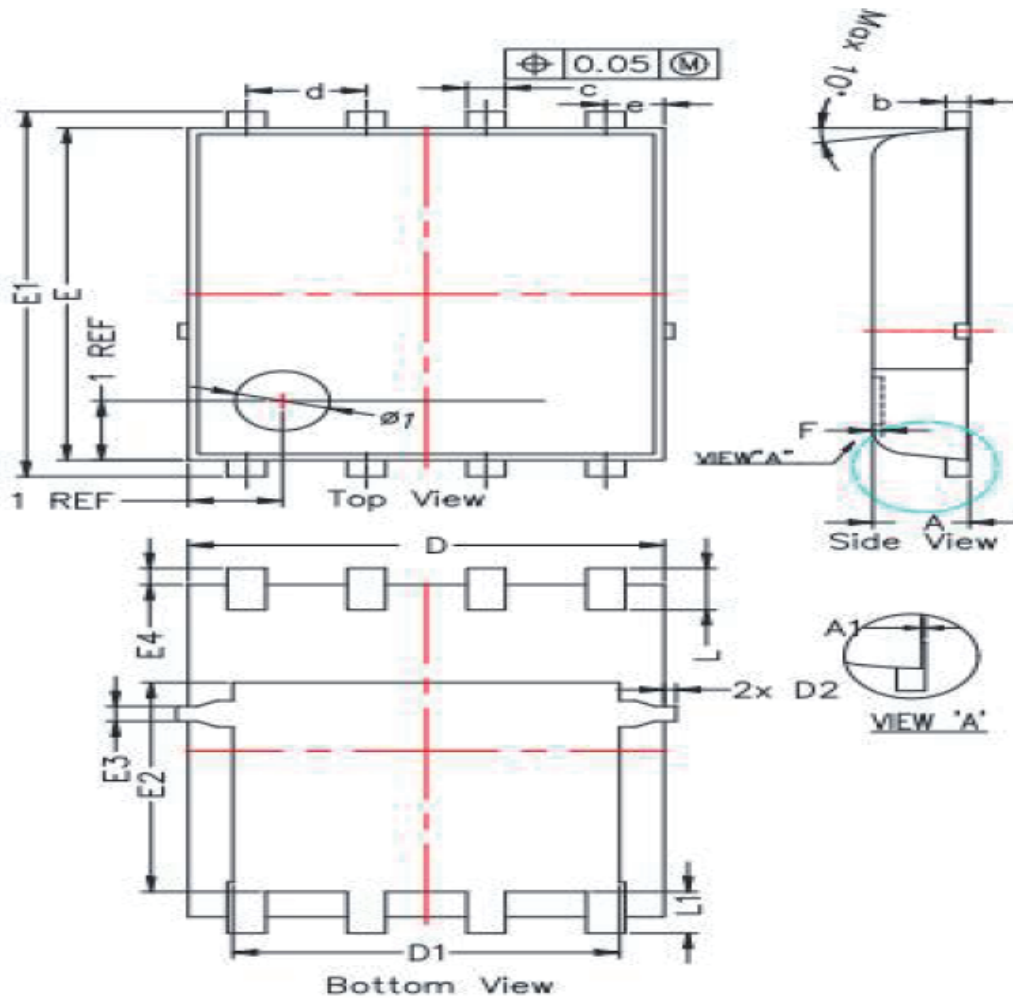


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms



| SYMBOLS | DIMENSION IN MM | | | DIMENSION IN INCHES | | |
|---------|-----------------|-------|-------|---------------------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| * A | 0.900 | 1.000 | 1.100 | 0.035 | 0.039 | 0.043 |
| A1 | 0.000 | --- | 0.050 | 0.000 | --- | 0.002 |
| b | 0.246 | 0.254 | 0.312 | 0.010 | 0.010 | 0.012 |
| * c | 0.310 | 0.410 | 0.510 | 0.012 | 0.016 | 0.020 |
| d | 1.27 BSC | | | 0.050 BSC | | |
| * D | 4.950 | 5.050 | 5.150 | 0.195 | 0.199 | 0.203 |
| D1 | 4.000 | 4.100 | 4.200 | 0.157 | 0.161 | 0.165 |
| * D2 | --- | --- | 0.125 | --- | --- | 0.005 |
| e | 0.62 BSC | | | 0.024 BSC | | |
| * E | 5.500 | 5.600 | 5.700 | 0.217 | 0.220 | 0.224 |
| * E1 | 6.050 | 6.150 | 6.250 | 0.238 | 0.242 | 0.246 |
| E2 | 3.425 | 3.525 | 3.625 | 0.135 | 0.139 | 0.143 |
| E3 | 0.150 | 0.250 | 0.350 | 0.006 | 0.010 | 0.014 |
| * E4 | 0.175 | 0.275 | 0.375 | 0.007 | 0.011 | 0.015 |
| F | - | - | 0.100 | - | - | 0.004 |
| * L | 0.500 | 0.600 | 0.700 | 0.02 | 0.02 | 0.03 |
| L1 | 0.600 | 0.700 | 0.800 | 0.02 | 0.03 | 0.03 |